

# EC2700ETTS-10.900M

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## REGULATORY COMPLIANCE (Data Sheet downloaded on Jul 16, 2019)


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## ITEM DESCRIPTION

Quartz Crystal Clock Oscillators XO (SPXO) LVCMOS (CMOS) 2.5Vdc 4 Pad 5.0mm x 7.0mm Ceramic Surface Mount (SMD) 10.900MHz  $\pm$ 100ppm -40°C to +85°C

## ELECTRICAL SPECIFICATIONS

Nominal Frequency	10.900MHz
Frequency Tolerance/Stability	$\pm$ 100ppm Maximum (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, Shock, and Vibration)
Aging at 25°C	$\pm$ 5ppm/year Maximum
Operating Temperature Range	-40°C to +85°C
Supply Voltage	2.5Vdc $\pm$ 5%
Input Current	4mA Maximum
Output Voltage Logic High (Voh)	90% of Vdd Minimum (IOH = -4mA)
Output Voltage Logic Low (Vol)	10% of Vdd Maximum (IOL = +4mA)
Rise/Fall Time	6nSec Maximum (Measured at 20% to 80% of waveform)
Duty Cycle	50 $\pm$ 10(%) (Measured at 50% of waveform)
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Pin 1 Connection	Tri-State (High Impedance)
Output Control Input Voltage Logic High (Vih)	90% of Vdd Minimum or No Connect to Enable Output
Output Control Input Voltage Logic Low (Vil)	10% of Vdd Maximum to Disable Output (High Impedance)
Standby Current	10 $\mu$ A Maximum (Disabled Output, High Impedance)
RMS Phase Jitter	1pSec Maximum (12kHz to 20MHz offset frequency)
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to +125°C

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A



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## OUTPUT WAVEFORM & TIMING DIAGRAM



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## Test Circuit for CMOS Output



Note 1: An external  $0.1\mu\text{F}$  low frequency tantalum bypass capacitor in parallel with a  $0.01\mu\text{F}$  high frequency ceramic bypass capacitor close to the package ground and  $V_{DD}$  pin is required.

Note 2: A low capacitance ( $<12\text{pF}$ ), 10X attenuation factor, high impedance ( $>10\text{Mohms}$ ), and high bandwidth ( $>300\text{MHz}$ ) passive probe is recommended.

Note 3: Capacitance value  $C_L$  includes sum of all probe and fixture capacitance.

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## Recommended Solder Reflow Methods



### High Temperature Infrared/Convection

<b><math>T_s \text{ MAX}</math> to <math>T_L</math> (Ramp-up Rate)</b>	$3^\circ\text{C/Second Maximum}$
<b>Preheat</b>	
- Temperature Minimum ( $T_s \text{ MIN}$ )	$150^\circ\text{C}$
- Temperature Typical ( $T_s \text{ TYP}$ )	$175^\circ\text{C}$
- Temperature Maximum ( $T_s \text{ MAX}$ )	$200^\circ\text{C}$
- Time ( $t_s \text{ MIN}$ )	60 - 180 Seconds
<b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>	$3^\circ\text{C/Second Maximum}$
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	$217^\circ\text{C}$
- Time ( $t_L$ )	60 - 150 Seconds
<b>Peak Temperature (<math>T_P</math>)</b>	$260^\circ\text{C Maximum for 10 Seconds Maximum}$
<b>Target Peak Temperature (<math>T_P \text{ Target}</math>)</b>	$250^\circ\text{C} +0/-5^\circ\text{C}$
<b>Time within <math>5^\circ\text{C}</math> of actual peak (<math>t_p</math>)</b>	20 - 40 Seconds
<b>Ramp-down Rate</b>	$6^\circ\text{C/Second Maximum}$
<b>Time <math>25^\circ\text{C}</math> to Peak Temperature (t)</b>	8 Minutes Maximum
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to body of device.

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## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 240°C

Ts MAX to TL (Ramp-up Rate)	5°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum (Ts MIN)	N/A
- Temperature Typical (Ts TYP)	150°C
- Temperature Maximum (Ts MAX)	N/A
- Time (ts MIN)	60 - 120 Seconds
<b>Ramp-up Rate (TL to TP)</b>	5°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature (TL)	150°C
- Time (tL)	200 Seconds Maximum
<b>Peak Temperature (TP)</b>	240°C Maximum
<b>Target Peak Temperature (TP Target)</b>	240°C Maximum 2 Times / 230°C Maximum 1 Time
<b>Time within 5°C of actual peak (tp)</b>	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
<b>Ramp-down Rate</b>	5°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	N/A
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to body of device.

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)